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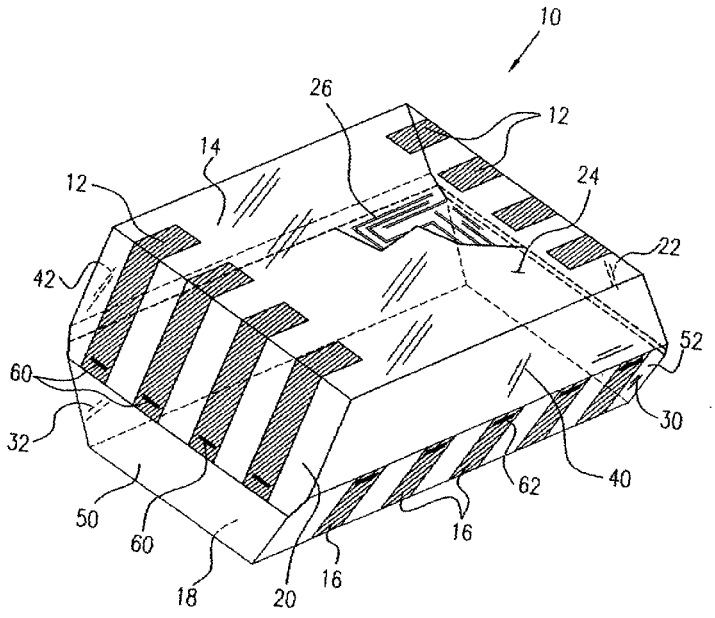
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(54) Title: PACKAGED INTEGRATED CIRCUITS AND METHODS OF PRODUCING THEREOF



(57) Abstract: A packaged integrated circuit and method for producing thereof, including an integrated circuit substrate lying in a substrate plane and having electrical circuitry formed thereon, a package enclosing the integrated circuit substrate and defining first and second planar surfaces generally parallel to the substrate plane and a plurality of electrical contacts, each connected to the electrical circuitry at the substrate plane, at least some of the plurality of electrical contacts extending onto the first planar surface and at least some of the plurality of electrical contacts extending onto the second planar surface.

WO 02/51217 A2

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